

74AUP2G34

Low-power dual buffer

Rev. 9 — 27 July 2023

Product data sheet

1. General description

The 74AUP2G34 is a dual buffer. Schmitt-trigger action at all inputs makes the circuit tolerant of slower input rise and fall times. This device ensures very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V. This device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- CMOS low power dissipation
- High noise immunity
- Overvoltage tolerant inputs to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation
- Latch-up performance exceeds 100 mA per JESD 78 Class II Level B
- Low static power consumption; $I_{CC} = 0.9 \mu A$ (maximum)
- Complies with JEDEC standards:
 - JESD8-12 (0.8 V to 1.3 V)
 - JESD8-11 (0.9 V to 1.65 V)
 - JESD8-7 (1.2 V to 1.95 V)
 - JESD8-5 (1.8 V to 2.7 V)
 - JESD8C (2.7 V to 3.6 V)
- ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 class 3A exceeds 5000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AUP2G34GW	-40 °C to +125 °C	TSSOP6	plastic thin shrink small outline package; 6 leads; body width 1.25 mm	SOT363-2
74AUP2G34GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AUP2G34GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74AUP2G34GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74AUP2G34GX	-40 °C to +125 °C	X2SON6	plastic thermal enhanced extremely thin small outline package; no leads; 6 terminals; body 1.0 × 0.8 × 0.32 mm	SOT1255-2

4. Marking

Table 2. Marking

Type number	Marking code[1]
74AUP2G34GW	aA
74AUP2G34GM	aA
74AUP2G34GN	aA
74AUP2G34GS	aA
74AUP2G34GX	aA

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

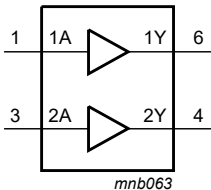


Fig. 1. Logic symbol

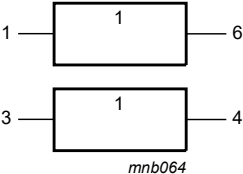


Fig. 2. IEC logic symbol

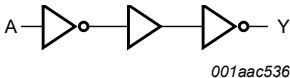


Fig. 3. Logic diagram

6. Pinning information

6.1. Pinning

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Pin configuration SOT363-2 (TSSOP6): A 6-pin package with pins 1A, GND, 2A on the left and 1Y, VCC, 2Y on the right. Pin 1A is at the top left, GND is in the middle left, and 2A is at the bottom left. On the right, 1Y is at the top, VCC is in the middle, and 2Y is at the bottom.

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Transparent top view

Pin configuration SOT886 (XSON6): A 6-pin package with pins 1A, GND, 2A on the left and 1Y, VCC, 2Y on the right. Pin 1A is at the top left, GND is in the middle left, and 2A is at the bottom left. On the right, 1Y is at the top, VCC is in the middle, and 2Y is at the bottom.

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001aad667

Transparent top view

Pin configuration SOT1115 and SOT1202 (XSON6): A 6-pin package with pins 1A, GND, 2A on the left and 1Y, VCC, 2Y on the right. Pin 1A is at the top left, GND is in the middle left, and 2A is at the bottom left. On the right, 1Y is at the top, VCC is in the middle, and 2Y is at the bottom.

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Transparent top view

Pin configuration SOT1255-2 (X2SON6): A 6-pin package with pins 1A, GND, 2A on the left and 1Y, VCC, 2Y on the right. Pin 1A is at the top left, GND is in the middle left, and 2A is at the bottom left. On the right, 1Y is at the top, VCC is in the middle, and 2Y is at the bottom.

Fig. 4. Pin configuration SOT363-2 (TSSOP6)

Fig. 5. Pin configuration SOT886 (XSON6)

Fig. 6. Pin configuration SOT1115 and SOT1202 (XSON6)

Fig. 7. Pin configuration SOT1255-2 (X2SON6)

6.2. Pin description

Table 3. Pin description

Symbol	Pin	Description
1A	1	data input
GND	2	ground (0 V)
2A	3	data input
2Y	4	data output
V _{CC}	5	supply voltage
1Y	6	data output

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level.

Input	Output
nA	nY
L	L
H	H

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage	[1]	-0.5	+4.6	V
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
V _O	output voltage	Active mode and Power-down mode [1]	-0.5	+4.6	V
I _O	output current	V _O = 0 V to V _{CC}	-	±20	mA
I _{CC}	supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C [2]	-	250	mW

- [1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.
[2] For SOT363-2 (TSSOP6) package: P_{tot} derates linearly with 3.7 mW/K above 83 °C.
For SOT886 (XSON6) package: P_{tot} derates linearly with 3.3 mW/K above 74 °C.
For SOT1115 (XSON6) package: P_{tot} derates linearly with 3.2 mW/K above 71 °C.
For SOT1202 (XSON6) package: P_{tot} derates linearly with 3.3 mW/K above 74 °C.
For SOT1255-2 (X2SON6) package: P_{tot} derates linearly with 3.3 mW/K above 75 °C.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		0.8	3.6	V
V _I	input voltage		0	3.6	V
V _O	output voltage	Active mode	0	V _{CC}	V
		Power-down mode; V _{CC} = 0 V	0	3.6	V
T _{amb}	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 0.8 V to 3.6 V	-	200	ns/V

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V	0.70 × V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	0.30 × V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.75 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.11	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.32	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	2.05	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.9	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.72	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.6	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.31	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.31	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.31	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.44	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.31	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.44	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.1	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.2	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.2	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	0.5	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	40	µA
C _I	input capacitance	V _{CC} = 0 V to 3.6 V; V _I = GND or V _{CC}	-	0.8	-	pF
C _O	output capacitance	V _O = GND; V _{CC} = 0 V	-	1.7	-	pF

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +85 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V	0.70 × V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	0.30 × V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.7 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.03	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.30	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.97	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.85	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.67	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.55	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.37	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.35	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.33	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.33	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.45	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.5	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.5	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.6	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	0.9	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	50	µA

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V	0.75 × V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	0.70 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V	-	-	0.25 × V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.30 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.11	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.6 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	0.93	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.17	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.77	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.67	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.40	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.30	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.11	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.33 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.41	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.39	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.36	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.50	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.36	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.50	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.75	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.75	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.75	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	1.4	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	75	µA

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 9.

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
C _L = 5 pF										
t _{pd}	propagation delay	nA to nY; see Fig. 8 [2]								
		V _{CC} = 0.8 V	-	14.9	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.6	4.7	9.2	2.0	10.0	2.0	11.0	ns
		V _{CC} = 1.4 V to 1.6 V	2.1	3.4	5.7	1.6	6.5	1.6	7.2	ns
		V _{CC} = 1.65 V to 1.95 V	1.8	2.9	4.5	1.4	5.2	1.4	5.8	ns
		V _{CC} = 2.3 V to 2.7 V	1.5	2.3	3.5	1.2	4.2	1.2	4.6	ns
		V _{CC} = 3.0 V to 3.6 V	1.4	2.1	3.2	1.0	3.8	1.0	4.2	ns
C _L = 10 pF										
t _{pd}	propagation delay	nA to nY; see Fig. 8 [2]								
		V _{CC} = 0.8 V	-	18.4	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.2	5.6	10.9	2.3	11.8	2.3	13.1	ns
		V _{CC} = 1.4 V to 1.6 V	2.6	4.1	6.7	1.9	7.7	1.9	8.5	ns
		V _{CC} = 1.65 V to 1.95 V	2.3	3.4	5.3	1.7	6.2	1.7	6.9	ns
		V _{CC} = 2.3 V to 2.7 V	2.0	2.9	4.2	1.5	5.0	1.5	5.5	ns
		V _{CC} = 3.0 V to 3.6 V	1.7	2.6	3.8	1.4	4.6	1.4	5.1	ns
C _L = 15 pF										
t _{pd}	propagation delay	nA to nY; see Fig. 8 [2]								
		V _{CC} = 0.8 V	-	21.9	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.6	6.4	12.6	2.6	13.8	2.6	15.2	ns
		V _{CC} = 1.4 V to 1.6 V	3.0	4.6	7.6	2.2	8.9	2.2	9.8	ns
		V _{CC} = 1.65 V to 1.95 V	2.6	3.9	6.0	2.0	7.2	2.0	7.9	ns
		V _{CC} = 2.3 V to 2.7 V	2.3	3.3	4.8	1.8	5.7	1.8	6.3	ns
		V _{CC} = 3.0 V to 3.6 V	2.1	3.1	4.2	1.6	5.0	1.6	5.5	ns
C _L = 30 pF										
t _{pd}	propagation delay	nA to nY; see Fig. 8 [2]								
		V _{CC} = 0.8 V	-	32.1	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	4.8	8.7	16.3	3.6	18.9	3.6	20.8	ns
		V _{CC} = 1.4 V to 1.6 V	4.0	6.2	10.3	3.4	12.2	3.4	13.4	ns
		V _{CC} = 1.65 V to 1.95 V	3.6	5.2	8.1	3.2	9.8	3.2	10.8	ns
		V _{CC} = 2.3 V to 2.7 V	3.0	4.4	6.4	2.7	7.7	2.7	8.5	ns
		V _{CC} = 3.0 V to 3.6 V	2.9	4.2	5.6	2.5	6.5	2.5	7.2	ns

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
C _L = 5 pF, 10 pF, 15 pF and 30 pF										
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _I = GND to V _{CC} [3][4]								
		V _{CC} = 0.8 V	-	2.5	-	-	-	-	-	pF
		V _{CC} = 1.1 V to 1.3 V	-	2.6	-	-	-	-	-	pF
		V _{CC} = 1.4 V to 1.6 V	-	2.7	-	-	-	-	-	pF
		V _{CC} = 1.65 V to 1.95 V	-	2.9	-	-	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	3.4	-	-	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	4.0	-	-	-	-	-	pF

- [1] All typical values are measured at nominal V_{CC}.
- [2] t_{pd} is the same as t_{PLH} and t_{PHL}.
- [3] All specified values are the average typical values over all stated loads.
- [4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
- P_D = C_{PD} × V_{CC}² × f_i × N + Σ(C_L × V_{CC}² × f_o) where:
- f_i = input frequency in MHz;
- f_o = output frequency in MHz;
- C_L = load capacitance in pF;
- V_{CC} = supply voltage in V;
- N = number of inputs switching;
- Σ(C_L × V_{CC}² × f_o) = sum of the outputs.

11.1. Waveform and test circuit

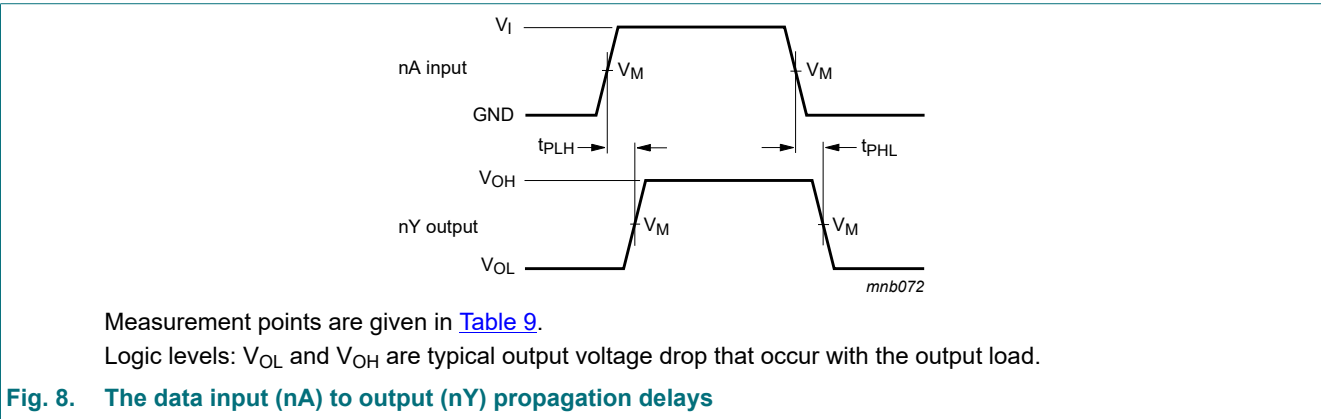
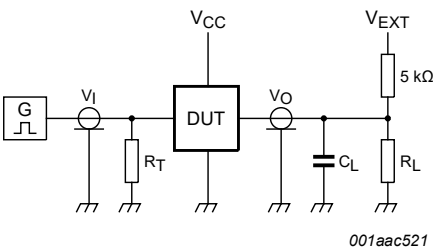


Table 9. Measurement points

Supply voltage	Output	Input		
V _{CC}	V _M	V _M	V _I	t _r = t _f
0.8 V to 3.6 V	0.5 × V _{CC}	0.5 × V _{CC}	V _{CC}	≤ 3.0 ns



Test data is given in [Table 10](#).
Definitions for test circuit:
 R_L = Load resistance;
 C_L = Load capacitance including jig and probe capacitance;
 R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator;
 V_{EXT} = External voltage for measuring switching times.

Fig. 9. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Load		V _{EXT}		
V _{CC}	C _L	R _L [1]	t _{PLH} , t _{PHL}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	2 × V _{CC}

[1] For measuring enable and disable times $R_L = 5\text{ k}\Omega$.
For measuring propagation delays, setup and hold times and pulse width $R_L = 1\text{ M}\Omega$.

12. Package outline

TSSOP6: plastic thin shrink small outline package; 6 leads; body width 1.25 mm SOT363-2

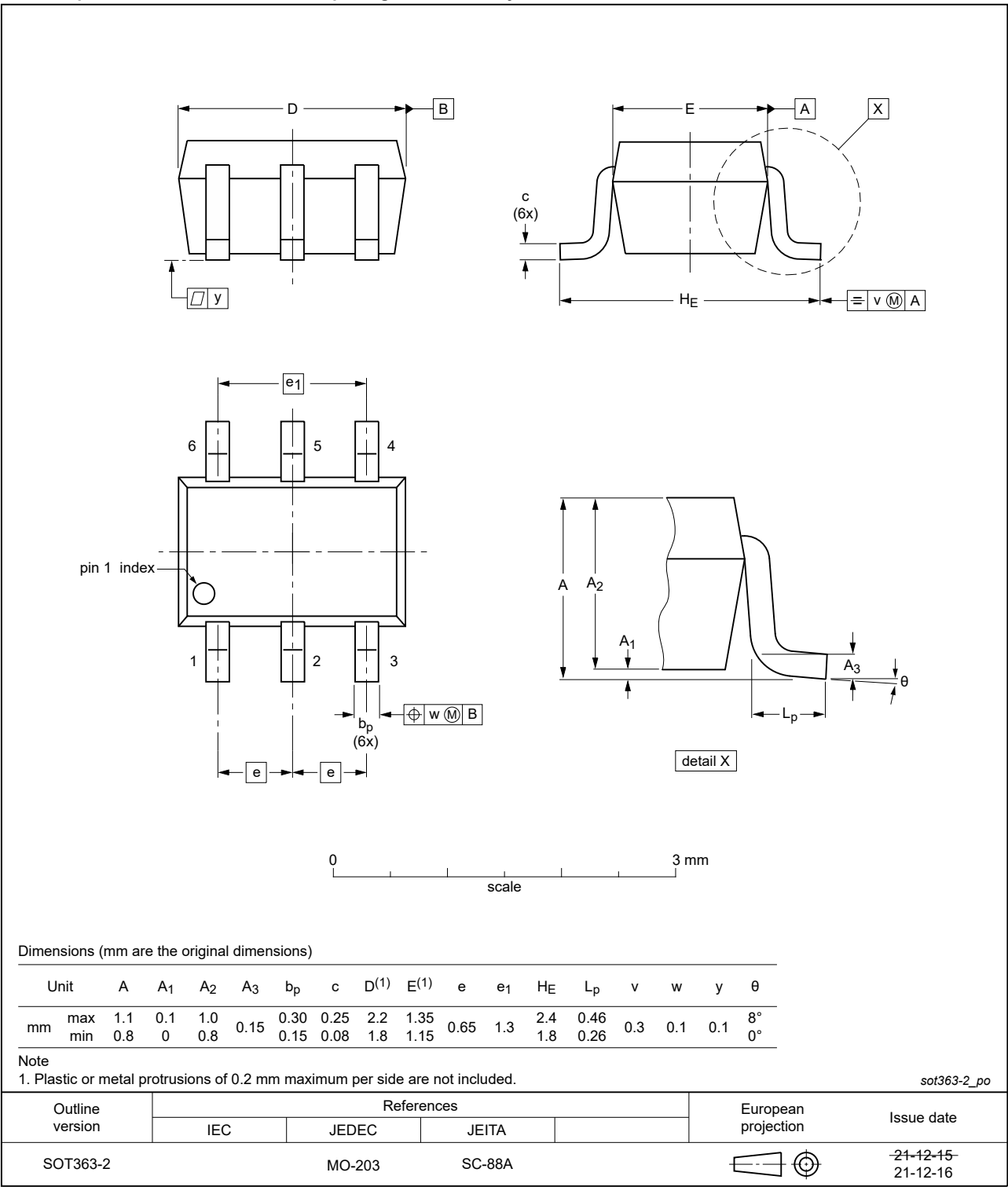


Fig. 10. Package outline SOT363-2 (TSSOP6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

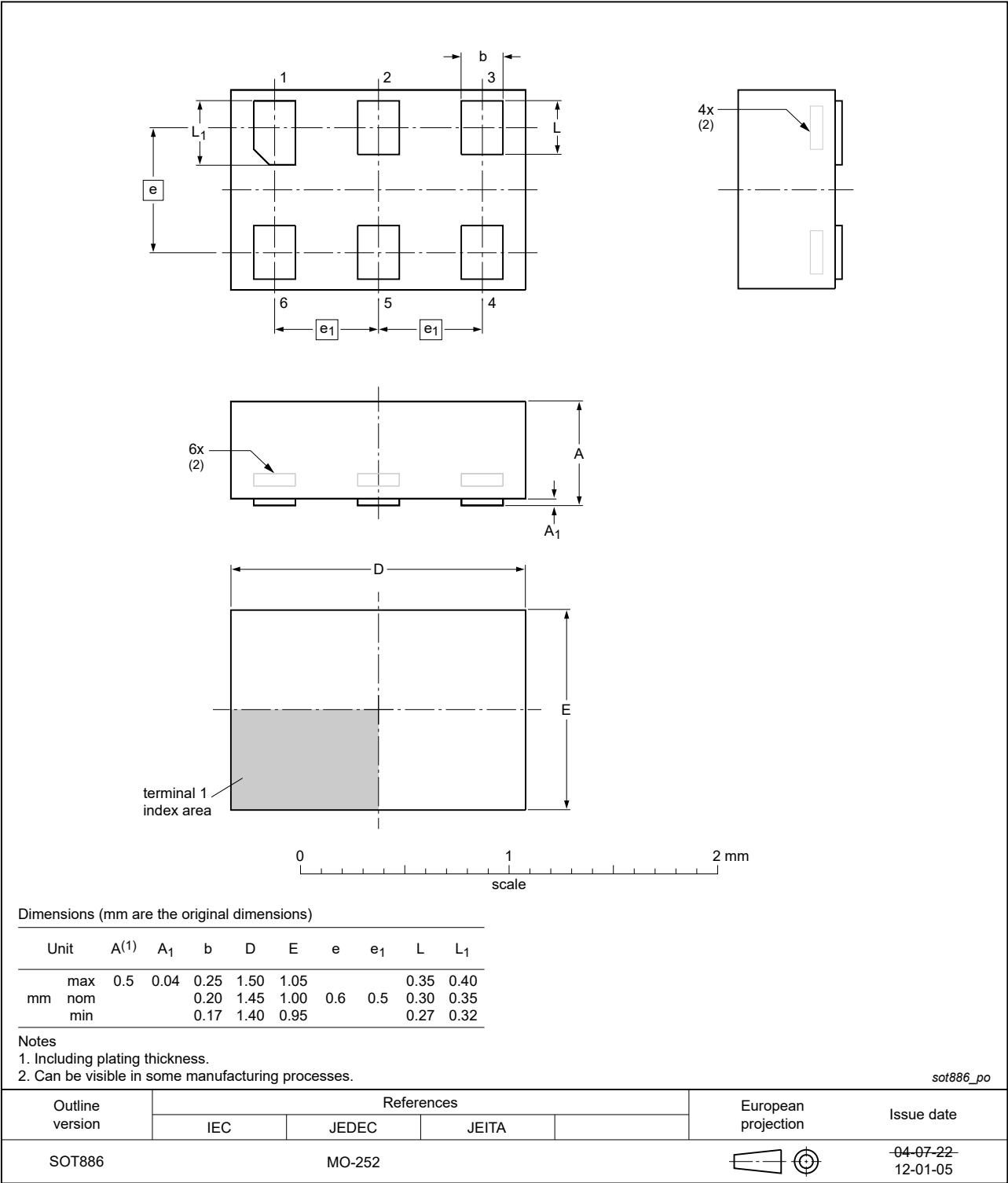


Fig. 11. Package outline SOT886 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115

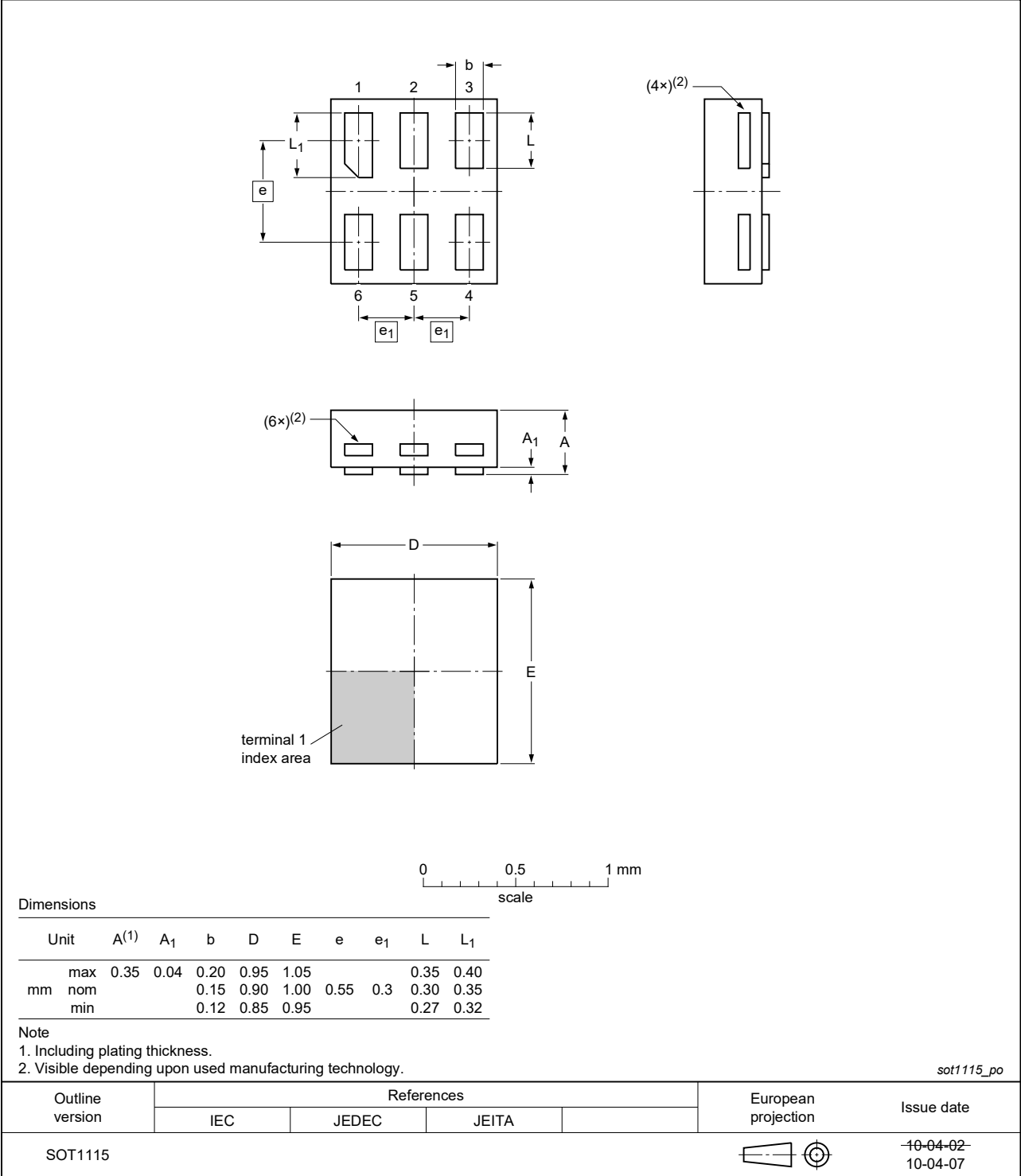


Fig. 12. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202

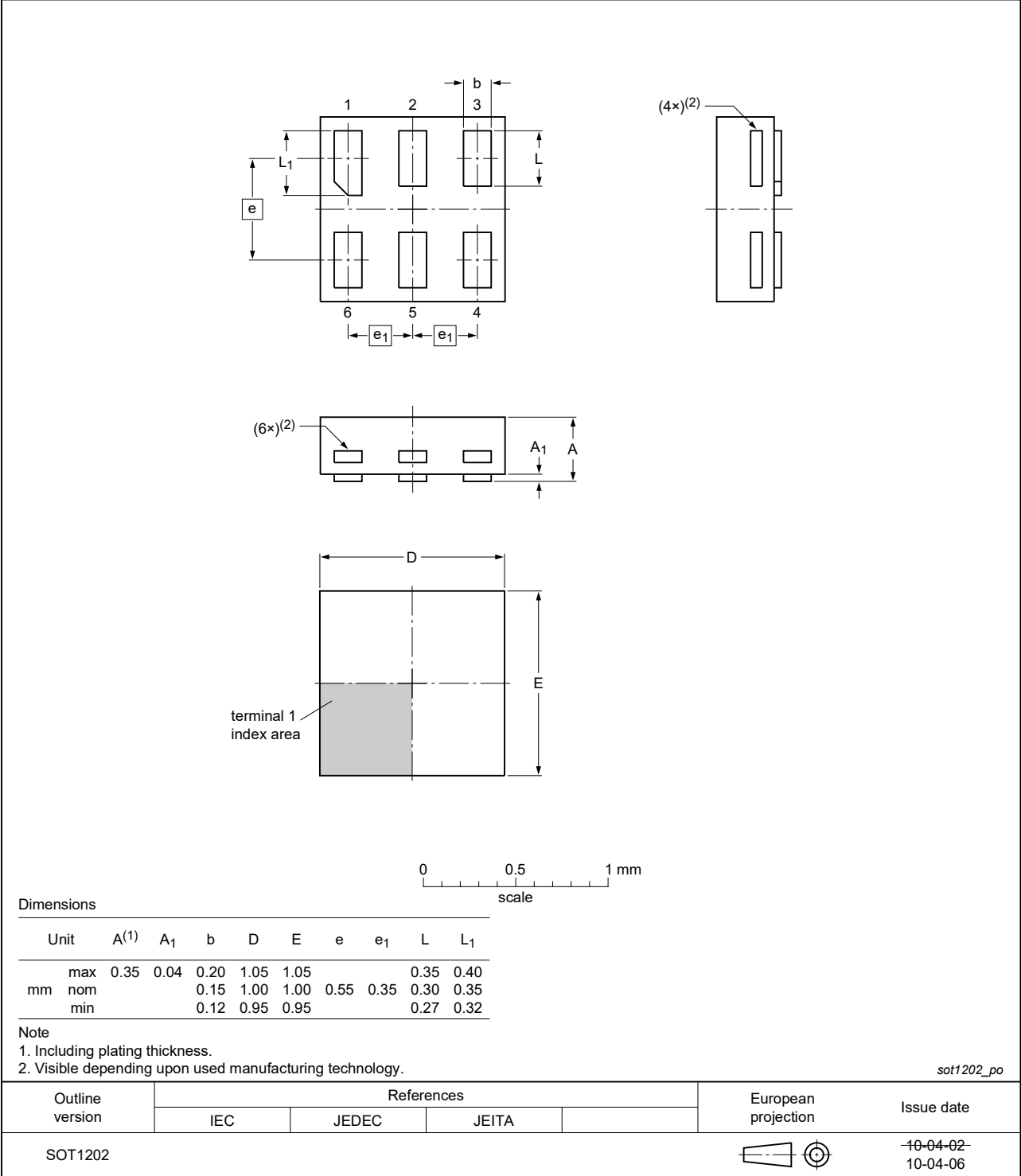


Fig. 13. Package outline SOT1202 (XSON6)

X2SON6: plastic thermal enhanced extremely thin small outline package; no leads;
6 terminals; body 1.0 x 0.8 x 0.32 mm

SOT1255-2

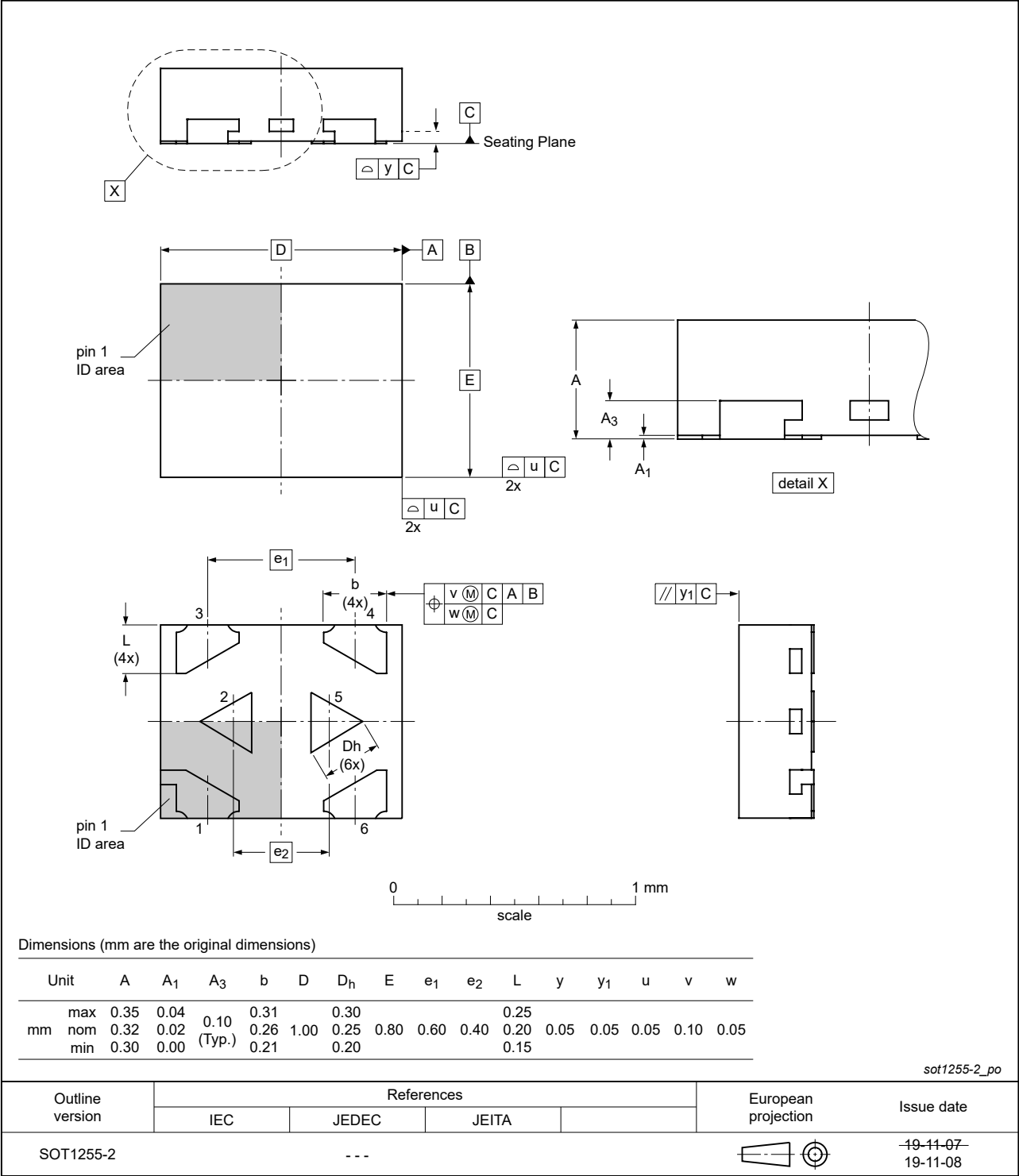


Fig. 14. Package outline SOT1255-2 (X2SON6)

13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model

14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP2G34 v.9	20230727	Product data sheet	-	74AUP2G34 v.8
Modifications:	<ul style="list-style-type: none">Section 2: ESD specification updated according to the latest JEDEC standard.			
74AUP2G34 v.8	20220131	Product data sheet	-	74AUP2G34 v.7
Modifications:	<ul style="list-style-type: none">SOT363 (SC-88) package changed to SOT363-2 (TSSOP6) package.			
74AUP2G34 v.7	20210707	Product data sheet	-	74AUP2G34 v.6
Modifications:	<ul style="list-style-type: none">SOT1255 (X2SON6) package changed to SOT1255-2 (X2SON6) package.Type number 74AUP2G34GF (SOT891/XSON6) removed.Table 5: Derating values for P_{tot} total power dissipation updated.			
74AUP2G34 v.6	20150917	Product data sheet	-	74AUP2G34 v.5
Modifications:	<ul style="list-style-type: none">Added type number 74AUP2G34GX (SOT1255/X2SON6).			
74AUP2G34 v.5	20130110	Product data sheet	-	74AUP2G34 v.4
Modifications:	<ul style="list-style-type: none">Package outline drawing of SOT886 (Fig. 11) modified.			
74AUP2G34 v.4	20111206	Product data sheet	-	74AUP2G34 v.3
Modifications:	<ul style="list-style-type: none">Legal pages updated.			
74AUP2G34 v.3	20100903	Product data sheet	-	74AUP2G34 v.2
74AUP2G34 v.2	20080131	Product data sheet	-	74AUP2G34 v.1
74AUP2G34 v.1	20061122	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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